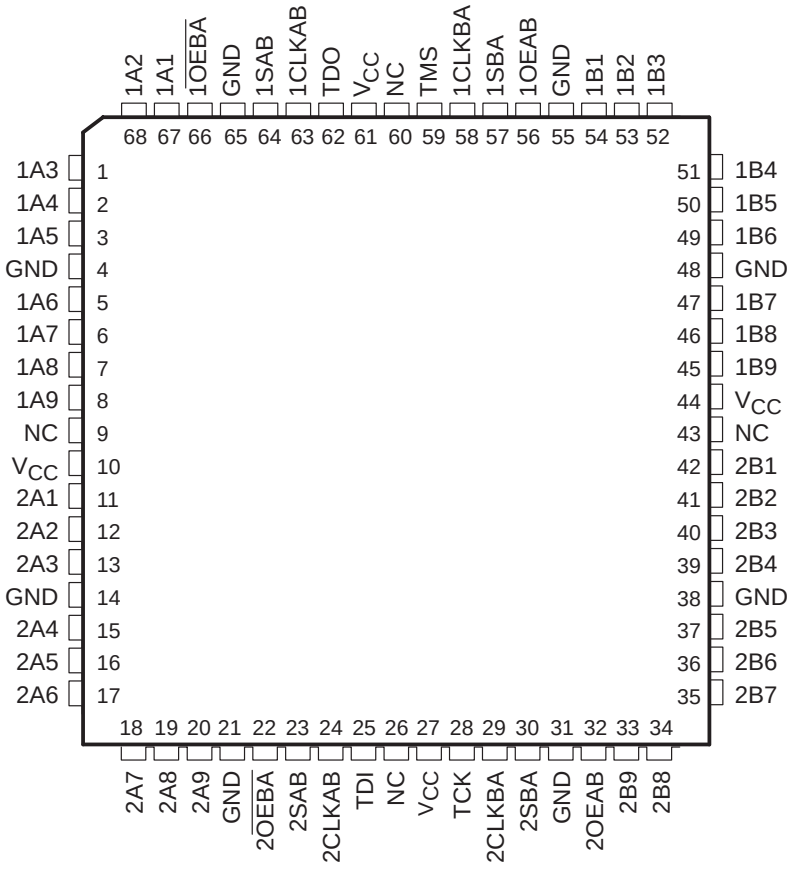
- **Members of the Texas Instruments *SCOPE*™ Family of Testability Products**
- **Members of the Texas Instruments *Widebus*™ Family**
- **Compatible With the IEEE Standard 1149.1-1990 (JTAG) Test Access Port and Boundary-Scan Architecture**
- **Include D-Type Flip-Flops and Control Circuitry to Provide Multiplexed Transmission of Stored and Real-Time Data**
- **Two Boundary-Scan Cells per I/O for Greater Flexibility**
- **State-of-the-Art *EPIC*-II*B*™ BiCMOS Design Significantly Reduces Power Dissipation**
- ***SCOPE*™ Instruction Set**
  - **IEEE Standard 1149.1-1990 Required Instructions, Optional INTEST, and P1149.1A CLAMP and HIGHZ**
  - **Parallel Signature Analysis at Inputs With Masking Option**
  - **Pseudo-Random Pattern Generation From Outputs**
  - **Sample Inputs/Toggle Outputs**
  - **Binary Count From Outputs**
  - **Device Identification**
  - **Even-Parity Opcodes**
- **Packaged in 64-Pin Plastic Shrink Quad Flat Pack (PM) and 68-Pin Ceramic Quad Flat Pack (HV)**

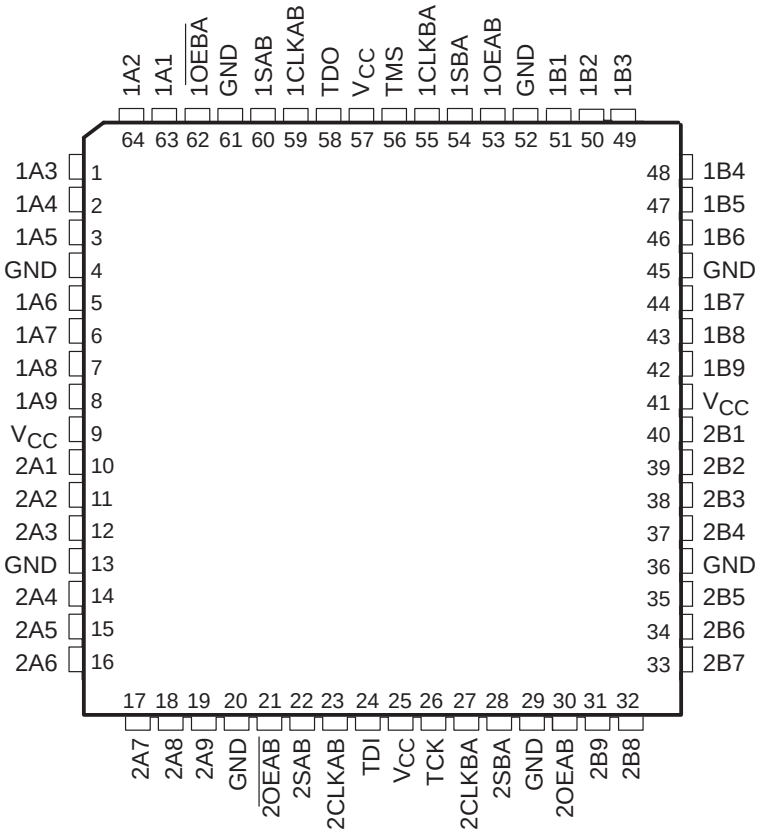
SN54ABT18652 . . . HV PACKAGE
(TOP VIEW)



NC – No internal connection

PRODUCT PREVIEW

SN74ABT18652 . . . PM PACKAGE
(TOP VIEW)



description

The SN54ABT18652 and SN74ABT18652 scan test devices with 18-bit bus transceivers and registers are members of the Texas Instruments SCOPE™ testability IC family. This family of devices supports IEEE Standard 1149.1-1990 boundary scan to facilitate testing of complex circuit board assemblies. Scan access to the test circuitry is accomplished via the 4-wire test access port (TAP) interface.

In the normal mode, these devices are 18-bit bus transceivers and registers that allow for multiplexed transmission of data directly from the input bus or from the internal registers. They can be used either as two 9-bit transceivers or one 18-bit transceiver. The test circuitry can be activated by the TAP to take snapshot samples of the data appearing at the device pins or to perform a self test on the boundary test cells. Activating the TAP in the normal mode does not affect the functional operation of the SCOPE™ bus transceivers and registers.

Data flow in each direction is controlled by clock (CLKAB and CLKBA), select (SAB and SBA), and output-enable (OEAB and $\overline{\text{OEBA}}$) inputs. For A-to-B data flow, data on the A bus is clocked into the associated registers on the low-to-high transition of CLKAB. When SAB is low, real-time A data is selected for presentation to the B bus (transparent mode). When SAB is high, stored A data is selected for presentation to the B bus (registered mode). When OEAB is high, the B outputs are active. When OEAB is low, the B outputs are in the high-impedance state. Control for B-to-A data flow is similar to that for A-to-B data flow but uses CLKBA, SBA, and $\overline{\text{OEBA}}$ inputs. Since the $\overline{\text{OEBA}}$ input is active-low, the A outputs are active when $\overline{\text{OEBA}}$ is low and are in the high-impedance state when $\overline{\text{OEBA}}$ is high. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the ′ABT18652.

PRODUCT PREVIEW

description (continued)

In the test mode, the normal operation of the SCOPE™ bus transceivers and registers is inhibited, and the test circuitry is enabled to observe and control the I/O boundary of the device. When enabled, the test circuitry can perform boundary scan test operations according to the protocol described in IEEE Standard 1149.1-1990.

Four dedicated test pins are used to observe and control the operation of the test circuitry: test data input (TDI), test data output (TDO), test mode select (TMS), and test clock (TCK). Additionally, the test circuitry can perform other testing functions such as parallel signature analysis on data inputs and pseudo-random pattern generation from data outputs. All testing and scan operations are synchronized to the TAP interface.

Additional flexibility is provided in the test mode through the use of two boundary scan cells (BSCs) for each I/O pin. This allows independent test data to be captured and forced at either bus (A or B). A PSA/COUNT instruction is also included to ease the testing of memories and other circuits where a binary count addressing scheme is useful.

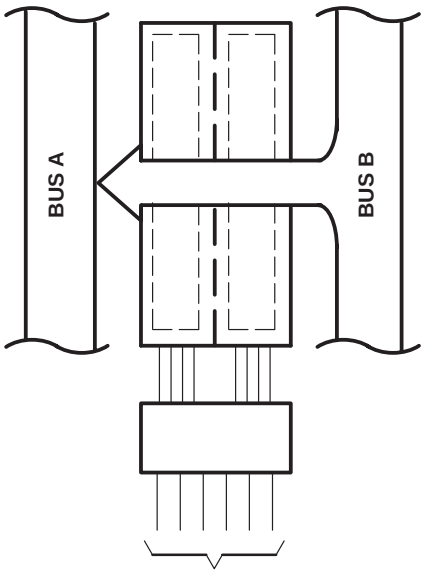
The SN54ABT18652 is characterized over the full military temperature range of –55°C to 125°C. The SN74ABT18652 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(normal mode, each 9-bit section)

INPUTS						DATA I/O		OPERATION OR FUNCTION
OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA	A1 THRU A9	B1 THRU B9	
L	H	L	L	X	X	Input disabled	Input disabled	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	L	X	X	Input	Unspecified†	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	L	↑	X	X	Unspecified†	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	L	X	H	X	Input	Output	Stored A data to B bus
H	L	L	L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

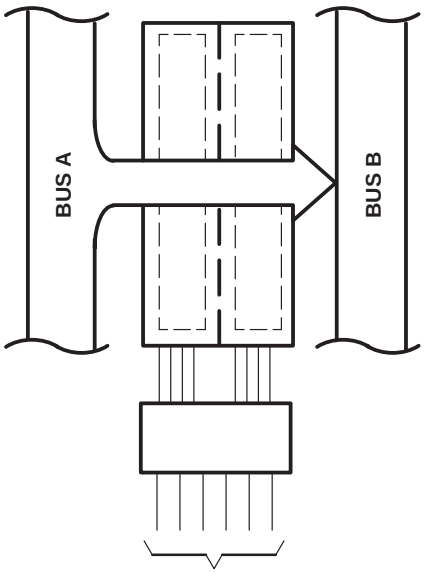
† The data output functions can be enabled or disabled by a variety of level combinations at the OEAB or $\overline{\text{OEBA}}$ inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition on the clock inputs.
‡ Select control = L: clocks can occur simultaneously.
Select control = H: clocks must be staggered in order to load both registers.

PRODUCT PREVIEW



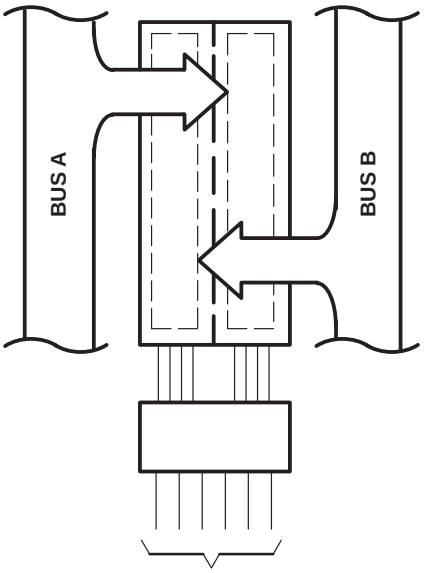
OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER
BUS B TO BUS A



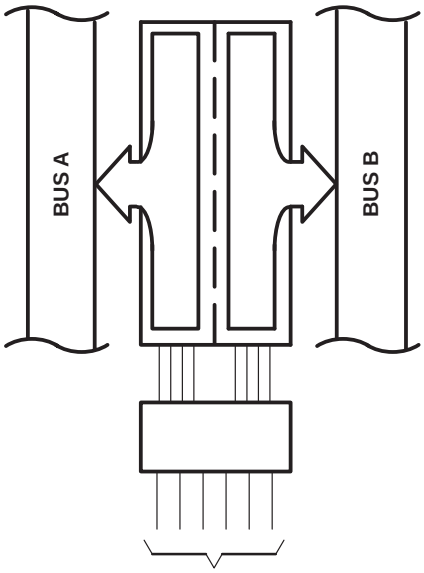
OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA
H	H	X	X	L	X

REAL-TIME TRANSFER
BUS A TO BUS B



OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

STORAGE FROM
A, B, OR A AND B

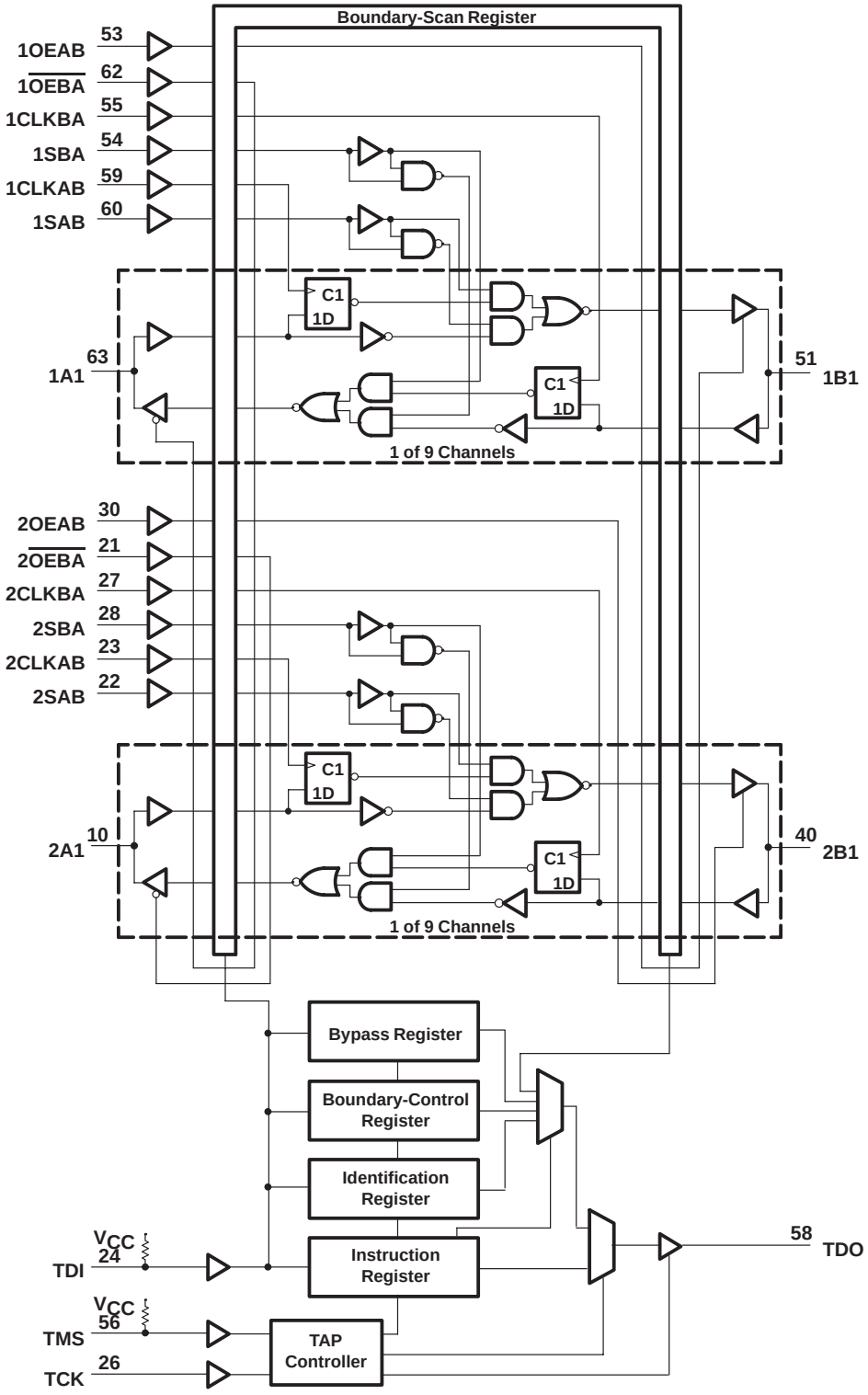


OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA
H	L	L	L	H	H

TRANSFER STORED DATA
TO A AND/OR B

Figure 1. Bus-Management Functions

functional block diagram



Pin numbers shown are for the PM package.

PRODUCT PREVIEW

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I: except I/O ports (see Note 1) . . . . . –0.5 V to 7 V
I/O ports (see Note 1) . . . . . –0.5 V to 5.5 V
Voltage range applied to any output in the high state or power-off state, V_O . . . . . –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT18652 . . . . . 96 mA
SN74ABT18652 . . . . . 128 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . –18 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . –50 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2) . . . . . 885 mW
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. For the SN74ABT18652 (PM package), the power derating factor for ambient temperatures greater than 55°C is –10.5 mW/°C.

recommended operating conditions (see Note 3)

		SN54ABT18652		SN74ABT18652		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused or floating pins (input or I/O) must be held high or low.

PRODUCT PREVIEW

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Note 4)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT18652		SN74ABT18652		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = – 3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = – 3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = – 24 mA		2			2				
		I_{OH} = – 32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
I_I	V_{CC} = 5.5 V, V_I = V_{CC} or GND		CLK, OEAB, OEBA, S, TCK			±1		±1		±1	µA
			A or B ports			±100		±100		±100	
I_{IH}	V_{CC} = 5.5 V,	V_I = V_{CC}	TDI, TMS			10		10		10	µA
I_{IL}	V_{CC} = 5.5 V,	V_I = GND	TDI, TMS			–160		–160		–160	µA
I_{OZH}‡	V_{CC} = 5.5 V,	V_O = 2.7 V				50		50		50	µA
I_{OZL}‡	V_{CC} = 5.5 V,	V_O = 0.5 V				–50		–50		–50	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 5.5 V				±100		±450		±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	A or B ports	Outputs high			4		4		4	mA
			Outputs low			80		80		80	
			Outputs disabled			4		4		4	
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V		Control inputs		4						pF
C_{io}	V_O = 2.5 V or 0.5 V		A or B ports		10						pF
C_o	V_O = 2.5 V or 0.5 V		TDO		8						pF

NOTE 4: Preliminary specifications based on SPICE analysis

* On products compliant to MIL-STD-883, Class B, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PRODUCT PREVIEW

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (normal mode) (see Note 4 and Figure 2)

			SN54ABT18652		SN74ABT18652		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	CLKAB or CLKBA	0	100	0	100	MHz
t_w	Pulse duration	CLKAB or CLKBA high or low			3		ns
t_{su}	Setup time	A before CLKAB↑ or B before CLKBA↑			5		ns
t_h	Hold time	A after CLKAB↑ or B after CLKBA↑			0		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (test mode) (see Note 4 and Figure 2)

			SN54ABT18652		SN74ABT18652		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	TCK	0	50	0	50	MHz
t_w	Pulse duration	TCK high or low			5		ns
t_{su}	Setup time	A, B, CLK, OEAB, $\overline{OEBA}$, or S before TCK↑			5		ns
		TDI before TCK↑			6		
		TMS before TCK↑			6		
t_h	Hold time	A, B, CLK, OEAB, $\overline{OEBA}$, or S after TCK↑			0		ns
		TDI after TCK↑			0		
		TMS after TCK↑			0		
t_d	Delay time	Power up to TCK↑			50		ns
t_r	Rise time	V_{CC} power up			1		µs

NOTE 4: Preliminary specifications based on SPICE analysis

PRODUCT PREVIEW

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (normal mode) (see Note 4 and Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT18652		SN74ABT18652		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}	CLKAB or CLKBA		100	130		100		100		MHz
t_{PLH}	A or B	B or A						1	6	ns
t_{PHL}								1	6	
t_{PLH}	CLKAB or CLKBA	B or A						2	6	ns
t_{PHL}								2	6	
t_{PLH}	SAB or SBA	B or A						2	8	ns
t_{PHL}								2	8	
t_{PZH}	OEAB or $\overline{OEBA}$	B or A						2	7.5	ns
t_{PZL}								2	7.5	
t_{PHZ}	OEAB or $\overline{OEBA}$	B or A						2	7.5	ns
t_{PLZ}								2	7.5	

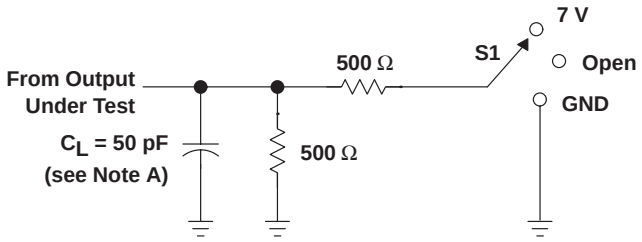
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (test mode) (see Note 4 and Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT18652		SN74ABT18652		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}	TCK		50	90		50		50		MHz
t_{PLH}	TCK↓	A or B						3	12	ns
t_{PHL}								3	12	
t_{PLH}	TCK↓	TDO						2	7	ns
t_{PHL}								2	7	
t_{PZH}	TCK↓	A or B						3	14	ns
t_{PZL}								3	14	
t_{PZH}	TCK↓	TDO						2	8	ns
t_{PZL}								2	8	
t_{PHZ}	TCK↓	A or B						3	14	ns
t_{PLZ}								3	14	
t_{PHZ}	TCK↓	TDO						2	8	ns
t_{PLZ}								2	8	

NOTE 4: Preliminary specifications based on SPICE analysis

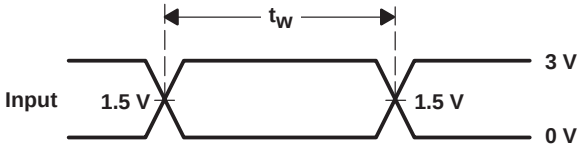
PRODUCT PREVIEW

PARAMETER MEASUREMENT INFORMATION

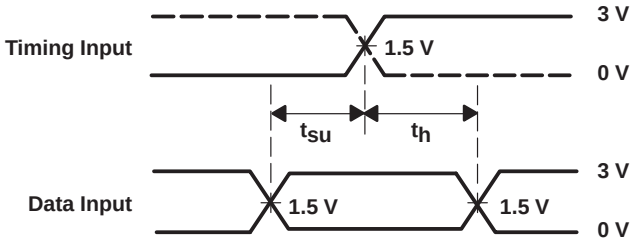


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

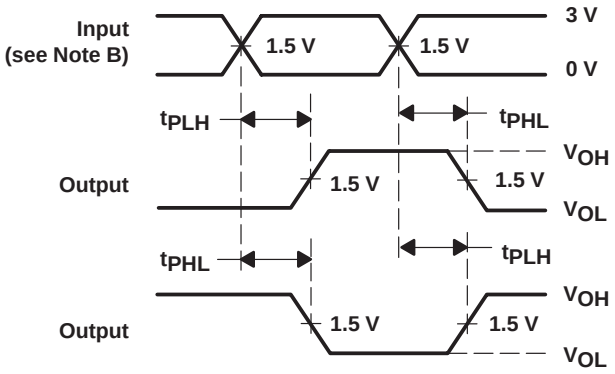
LOAD CIRCUIT FOR OUTPUTS



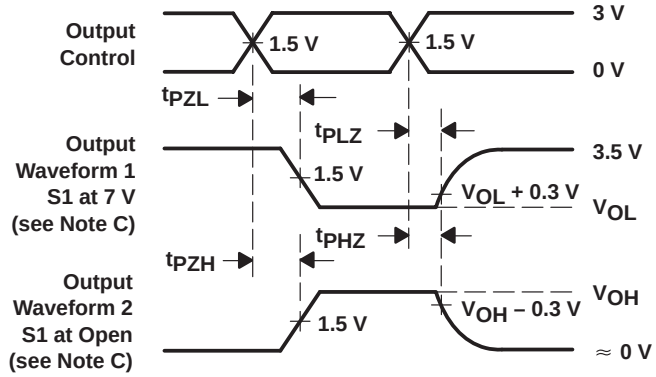
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NON-INVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PRODUCT PREVIEW

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